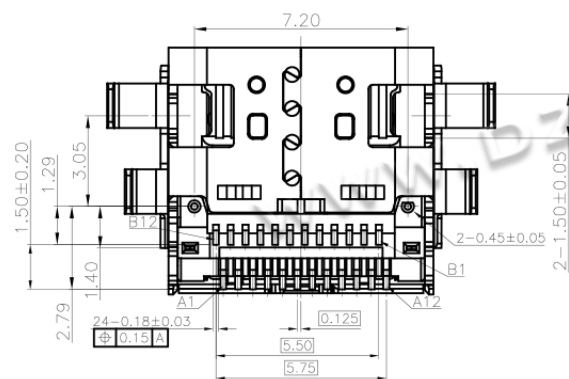
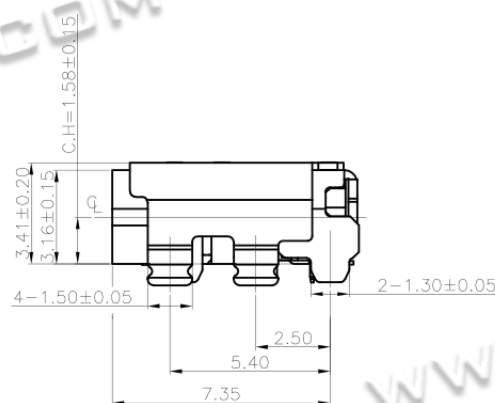
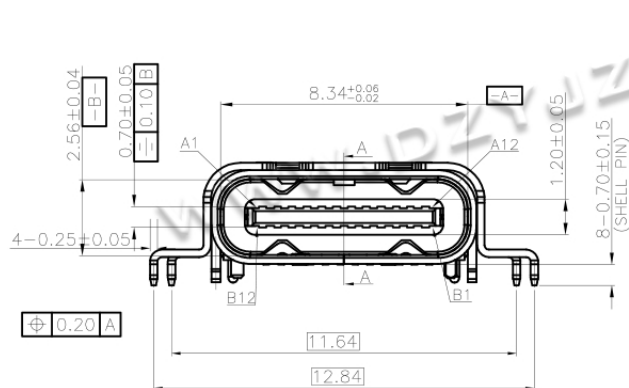
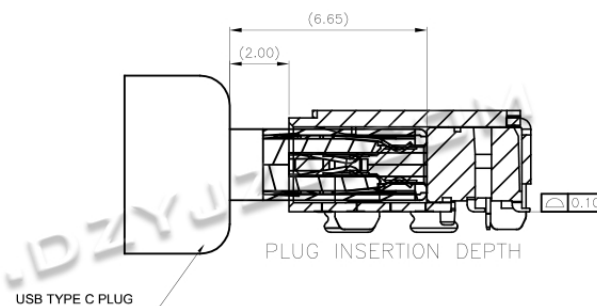
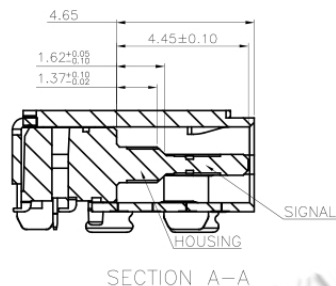
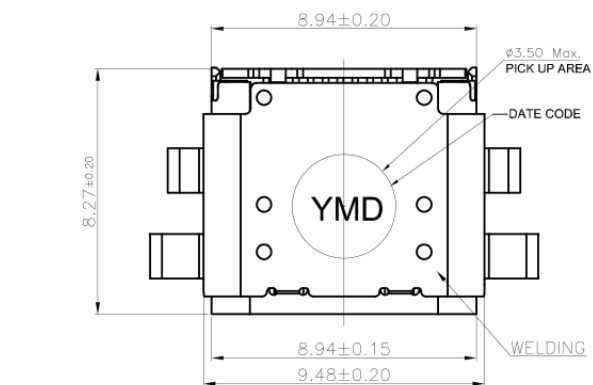


6	OUT SHELL	1	SUS304	30U" NICKEL PLATING	0.25mm
5	INT SHELL	1	SUS304	30U" NICKEL PLATING	0.3mm
4	MAIN HOUSING	1	HIGH TEMPERATURE	PA9T BLACK	UL94V-0
3	MID PLATE	1	SUS301	30U" NICKEL PLATING	0.15mm
2	BOTTOM TERMINAL	1	COPPER ALLOY	MATING SIDE:SEE PART NO	
1	TOP TERMINAL	1	COPPER ALLOY	SOLDER TAIL:Gold FLASH, 50u" NICKEL OVERALL	0.12mm
ITEM	DESCRIPTION	QTY	MATERIAL	FINISH	REMARK



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TOLERANCE:

X.X ±0.30

X.XX ±0.25

X.XXX ±0.15

X." ±2"

X.X" ±0.5"

UNIT: mm [inch]

SCALE:1:1

SIZE: A4

DRAWN BY :

陈一鸣

CHECKED BY :

马跃

APPROVED BY :

邱敏

DATE :

2014-02-23

DATE :

2014-02-23

DATE :

2014-02-23

PART NAME: USB TYPE C 4.0母座24P

双壳双贴板上SMT 有DIP脚CH=1.57 L=8.17

PART NO.

HYC472-USBC24-817

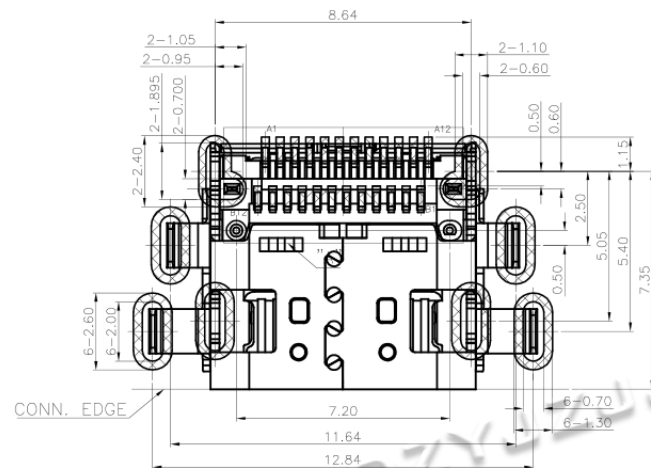
MOLD NO.

DRAW NO:

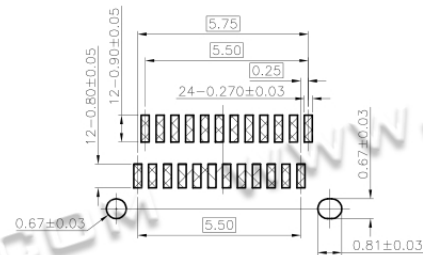
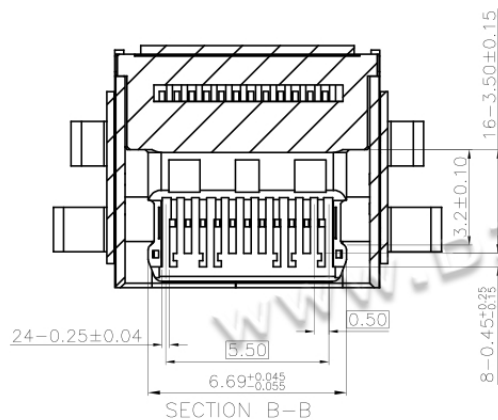
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SHEET NO.

1 OF 1

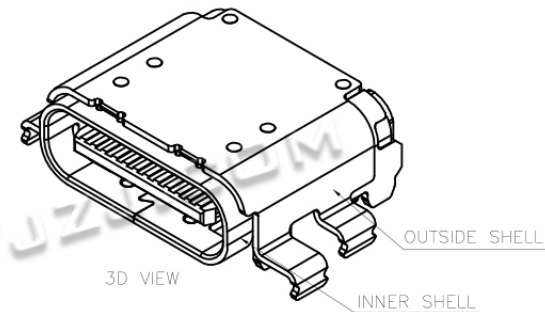


RECOMMENDED PCB LAYOUT(TOP VIEW)
(TOLERANCE=±0.05mm THICKNESS=0.8mm)



USB TYPE-C PIN ASSIGNMENTS:

A12	GND	B1	GND
A11	SSRxp2	B2	SSTxp2
A10	SSRxn2	B3	SSTxn2
A9	VBUS	B4	VBUS
A8	SBU1	B5	CC2
A7	Dn1	B6	Dp2
A6	Dp1	B7	Dn2
A5	CC1	B8	SBU2
A4	VBUS	B9	VBUS
A3	SSTxn1	B10	SSRxn1
A2	SSTxp1	B11	SSRxp1
A1	GND	B12	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME



NOTES:

1. MATERIAL:

- 1.1 OUTSIDE SHELL: SUS301R-1/2H T=0.25mm
- 1.2 INNER SHELL: SUS301R-1/2H T=0.30mm
- 1.3 SIGNAL: SUS301R-H T=0.15mm
- 1.5 HOUSING: PA9T+45%G.F. UL94V-0 BLACK
- 1.6 TERNARL: C19400 T=0.12mm

2. PLATING:

- 2.1 TERMINAL: SEE PIN
- 2.2 SHELL&SIGNAL: NICKEL PLATED 50u"MIN.

3. ELECTRICAL CHARACTERISTICS:

- 3.1 CURRENT RATING: 5.0 A
VOLTAGE RATING: 20.0 V
- 3.2 LLCR: VBUS& GND PINS: 40mΩ/PIN MAX
OTHER PINS : 40mΩ/PIN MAX
LLCR MAX. CHANGE OF ALL PINS: 10mΩ
- 3.3 INSULATION RESISTANCE: 100MΩ MIN.

4. MECHANICAL CHARACTERISTICS:

- 4.1 INSERTION FORCE: 0.5~2.0kg.
- 4.2 WITHDRAWAL FORCE: 0.8~2.0kg.(INITIAL) 0.6~2.0kg.(AFTER LIFE TEST)
5. LIFE TEST: 10000 CYCLES MIN

TERMINAL PLATING CODE:

- 1: GOLD FLASH ON MATING AREA, AND ON SOLDERING AREA, 50u"Min. NICKEL UNDER PLATING OVERALL
- 5: 30u" Au ON MATING AREA, GOLD FLASH ON SOLDERING AREA, 50u"Min. NICKEL UNDER PLATING OVERALL



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TOLERANCE:
X.X ±0.30
X.XX ±0.25
X.XXX ±0.15
X.X' ±2" X.X' ±0.5"



UNIT: mm [inch]
SCALE: 1:1 SIZE: A4

DRAWN BY :
陈一鸣

CHECKED BY:
马跃

APPROVED BY:
邱敏

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2014-02-23

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DATE :
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PART NAME: USB TYPE C 4.0母座24P
双壳双贴板上SMT 有DIP脚CH=1.57 L=8.17

PART NO.
HYC472-USBC24-817

MOLD NO.

DRAW NO:
HYC-2310121558

SHEET NO.
1 OF 1